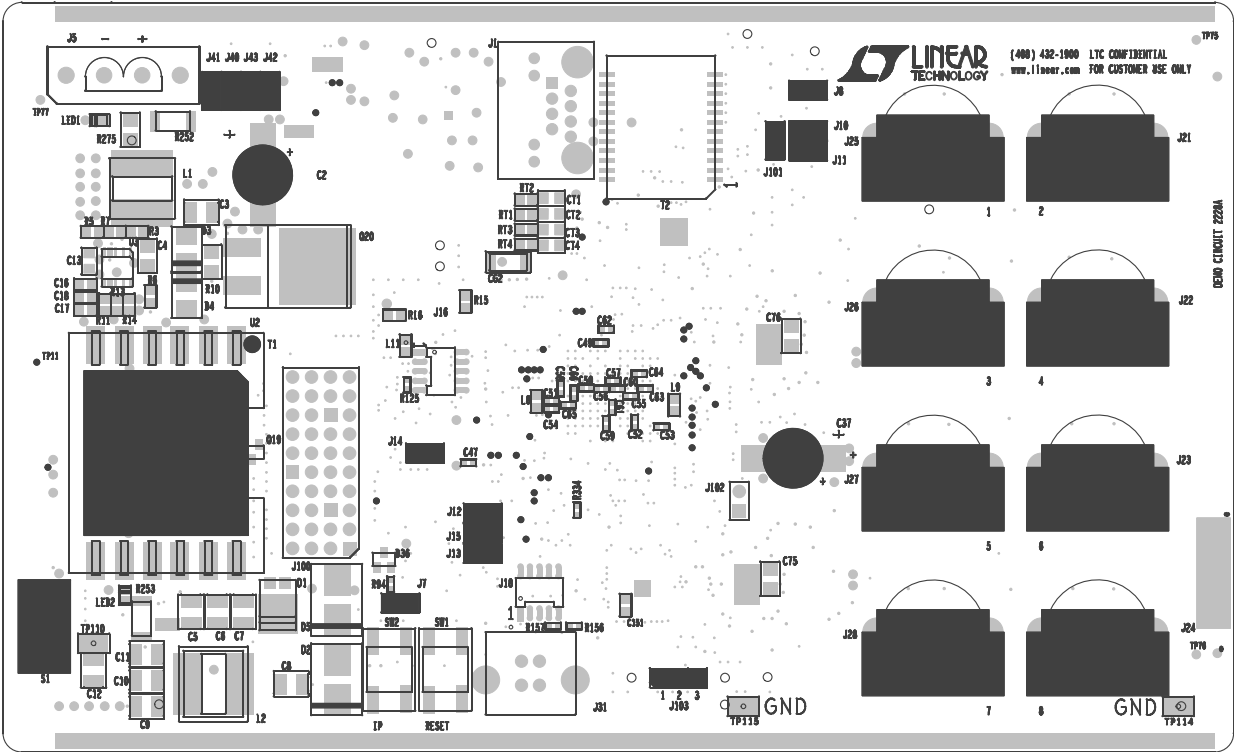



REVISION HISTORY				
ECO	REV	DESCRIPTION	APPROVED	DATE
-	3	3RD PROTOTYPE	KEITH B.	12-2-14

NOTES: UNLESS OTHERWISE SPECIFIED

- 1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
- 2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER SMD BOTH SIDES. MAXIMUM SOLDER TEMPERATURE IS 240 DEGREES CELSIUS.
- 3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
- 4. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
- 5. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.



APPROVALS		 <div>1630 McCarthy Blvd. Milpitas, CA 95035 Phone: (408) 432-1900 Fax: (408) 434-2507 www.linear.com</div>		LTC CONFIDENTIAL FOR CUSTOMER USE ONLY	
PCB DES.	TECONCEPT				
APP ENG.	KEITH B.				
		TITLE: BOTTOM ASSEMBLY DRAWING IO-LINK DEMONSTRATOR			
		SIZE N/A	IC NO. LTC2874IUHF DEMO CIRCUIT 2228A		REV. 3
SCALE = 1:1		DATE: Tuesday December 2, 2014		SHEET 1 OF 1	